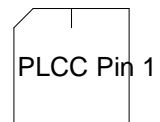



Relative Orientations



- ① Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. 17µm [1/2 oz.] Cu clad. SnPb plating.
- ③ Pins: shell material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.). Contact material- BeCu; finish 0.25µm [10µ"] Au over 2.54µm [100µ"] Ni (min.).
- ④ Leads: material- BeCu Alloy 194; plating- 60/40 SnPb 3.80-10.16µm [150-400µ"].

Package convertor (PC); 48 pos. Dip female socket to 68 pos. PLCC plug. Pin assignment; specific for Zilog Z8001 micro controllers.

PC-DIP/PLCC-8001-P-01 Drawing		Status: Released	Scale: 2:1	Rev: B
 <p>© 1995 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com</p>	Drawing: M. Tully		Date: 3/1/92	
	File: PC-DIP/PLCC-8001-P-01 Dwg			ECO#